Broadcom and Toppan open Singaporeâ??s first advanced chip substrate plant in Jurong

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Advanced Substrate Technologies (AST), the Broadcom and Toppan Holdings joint venture, officially opened Singaporeâ??s first high-end Flip Chip Ball Grid Array (FC-BGA) substrate plant in Jurong Lake District on Tuesday, 29 September 2026, Broadcom said.

The Advanced Substrate Technologies facility in Singapore, opened 29 September 2026. Photo: AST via Broadcom

It is the first plant in Singapore able to make high-end FC-BGA substrates, and Toppanâ??s first outside Japan. The substrates connect AI, networking and high-performance computing chips to circuit boards, and are in short supply worldwide. The 95,000 sq m plant is at 9 Pesawat Drive in Jurong Lake District.

Workforce and ramp

AST has already hired more than 300 staff in Singapore, including engineers and technicians, and will keep recruiting as high-volume manufacturing begins later in 2026. Broadcom is both joint-venture partner and primary customer for the substrates.

AST chief executive Yoshiyuki Iida said the investment reflects a long-term commitment to Singapore as a manufacturing hub and to supply-chain resilience. Charlie Kawwas, president of Broadcomâ??s

semiconductor solutions group, said the Singapore FC-BGA capacity gives the company flexibility while the industry remains short of advanced substrates.

Deputy Prime Minister Gan Kim Yong, who is also Minister for Trade and Industry (Trade), attended the opening. â??As technology advances and global competition intensifies, we must build on this foundation and develop capabilities that are difficult to replicate,â?• Mr Gan said.

He said AST will create more than 330 jobs, including engineering and skilled technician positions, and plans to carry out research and development in Singapore. Output is due to rise in a later expansion phase.

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